

ABSTRACT

One embodiment comprises a substrate having a top surface for receiving a semiconductor die. According to a disclosed embodiment, an inductor is patterned on the top surface of the substrate. The inductor is easily accessible by connecting its first and second terminals to, respectively, a substrate signal bond pad and a semiconductor die signal bond pad. In another disclosed embodiment, an inductor is fabricated within the substrate. The inductor comprises via metal segments connecting interconnect metal segments on the top and bottom surfaces of the substrate. The first and second terminals of the inductor are easily accessible through first and second substrate signal bond pads.

One embodiment comprises at least one via in the substrate. The at least one via provides an electrical connection between a signal bond pad of the semiconductor die and a printed circuit board attached to the bottom surface of the substrate.